



Features

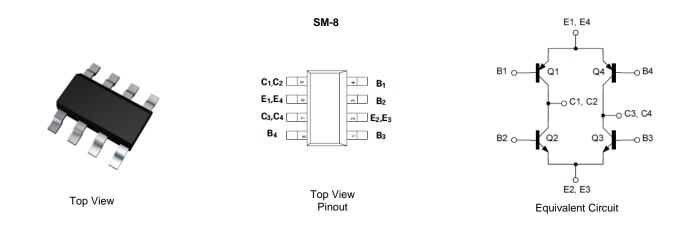
- BJT H-Bridge
- 2 x NPN + 2 x PNP
- I_c = 2.5A Continuous Collector Current
- NPN Transistor
 - BV_{CEO} > 20V
 - Low Saturation Voltage V_{CE(sat)} < 150mV @ 1A
 - PNP Transistor
 - BV_{CEO} > -20V
 - Low Saturation Voltage V_{CE(sat)} < -200mV @ -1A
 - Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SM-8 (8 LEAD SOT223)
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0

20V BIPOLAR TRANSISTOR H-BRIDGE IN SM-8

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.117 grams (Approximate)



Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
ZHB6718TA	ZHB6718	7	12	1,000

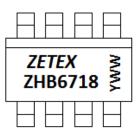
Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



ZHB6718 = Product Type Marking Code YWW = Date Code Marking Y or \overline{Y} = Last Digit of Year (ex: 5= 2015) WW or \overline{WW} = Week Code (01~53)



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit
Collector-Base Voltage	V _{CBO}	20	-20	V
Collector-Emitter Voltage	V _{CEO}	20	-20	V
Emitter-Base Voltage	V _{EBO}	7	-7	V
Continuous Collector Current	IC	2.5	-2.5	A
Peak Pulse Current (Note 5)	I _{CM}	6	-6	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Collector Bower Dissinction	(Note 5)	Р	1.25	w	
Collector Power Dissipation	(Note 6)	P _D	2	vv	
Thermal Desistance, Junction to Ambient	(Note 5)	D	100	0000	
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	62.5	°C/W	
Thermal Resistance, Junction to Lead		R _{θJL}	62	°C/W	
Operating and Storage Temperature Range		T _J ,T _{STG}	-55 to +150	°C	

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

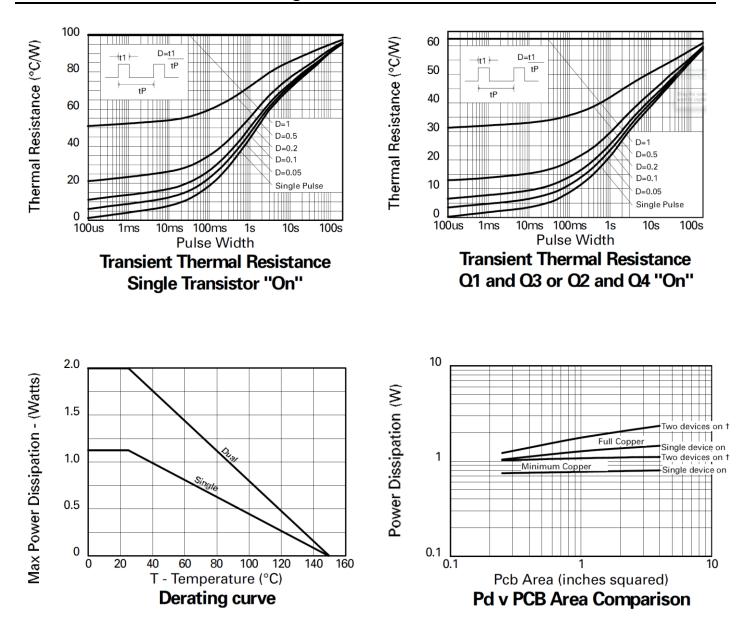
5. For a device with any single die active and mounted with the collector lead on 25mm x 25mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state. Notes:

Same as Note (5), except both Q1/Q3 active or Q2/Q4 active and equally sharing power.
 Refer to JEDEC specification JESD22-A114 and JESD22-A115.



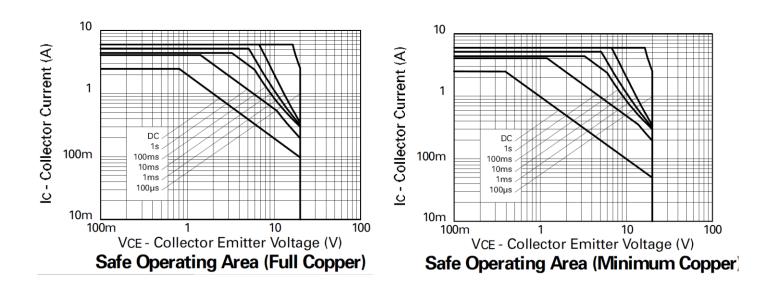
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Thermal Characteristics and Derating Information





Thermal Characteristics and Derating Information (continued)



Note: The Safe Operating Area (SOA) charts shown are a combination of the worst case secondary breakdown characteristics for the NPN/PNP pair, and the thermal curves demonstrating the power dissipation capability of the energized ZHB part (opposing NPN-PNP switched on) when mounted on a 50mm × 50mm FR4 PCB. The two cases show:

ii) with minimal copper present — this being defined as an SM-8 footprint with 1.5mm tracks to the edge of the PCB.

For example, on a 50mm x 50mm full copper PCB, the ZHB6718 will safely dissipate 2W under DC conditions, taking note of continuous current ratings and voltage limits. Higher powers can be tolerated for pulsed operation, while the shorter pulse widths (100µs and 1ms) being relevant for assessment of switching conditions.

i) full copper present and



Characteristic Symbol Min Max Unit **Test Condition** Тур Collector-Base Breakdown Voltage 20 100 V $\mathsf{BV}_{\mathsf{CBO}}$ $I_{C} = 100 \mu A$ Collector-Emitter Breakdown Voltage (Note 8) 20 27 V $\mathsf{BV}_{\mathsf{CEO}}$ $I_C = 10 mA$ _ Emitter-Base Breakdown Voltage 5 8.3 ۷ $I_{E} = 100 \mu A$ BVEBO ____ Collector Cut Off Current Ісво ____ 0.1 μΑ $V_{CB} = 16V$ ____ Emitter Cut Off Current 0.1 μΑ $V_{EB} = 4V$ IEBO _ ____ 200 400 $I_C = 10mA$, $V_{CE} = 2V$ ____ $I_{C} = 100 \text{mA}, V_{CE} = 2 \text{V}$ 450 300 DC Current Transfer Static Ratio (Note 8) h_{FE} 200 360 $I_C = 2A, V_{CE} = 2V$ 180 ____ _ $I_C = 6A, V_{CE} = 2V$ 8 _ 15 $I_{C} = 0.1A, I_{B} = 10mA$ Collector-Emitter Saturation Voltage (Note 8) 70 150 m٧ $I_{\rm C} = 1$ A, $I_{\rm B} = 10$ mA V_{CE(sat)} _ 130 200 $I_{C} = 2.5A, I_{B} = 50mA$ V Base-Emitter Saturation Voltage (Note 8) V_{BE(sat)} 0.89 1.0 _ $I_{C} = 2.5A, I_{B} = 50mA$ V $I_{C} = 2.5A, V_{CE} = 2V$ Base-Emitter Turn-on Voltage (Note 8) 0.79 V_{BE(on)} ____ ____ $I_{C} = 50 \text{mA}, V_{CE} = 10 \text{V},$ Transitional Frequency f⊤ 100 140 MHz f = 100 MHz**Output Capacitance** C_{obo} _ 23 30 pF $V_{CB} = 10V, f = 1MHz$ 170 nS t_(ON) _ ____ $V_{CC} = 10V, I_C = 1A,$ Switching Time $I_{B1} = -I_{B2} = 10mA$ 400 nS t_(Off) _

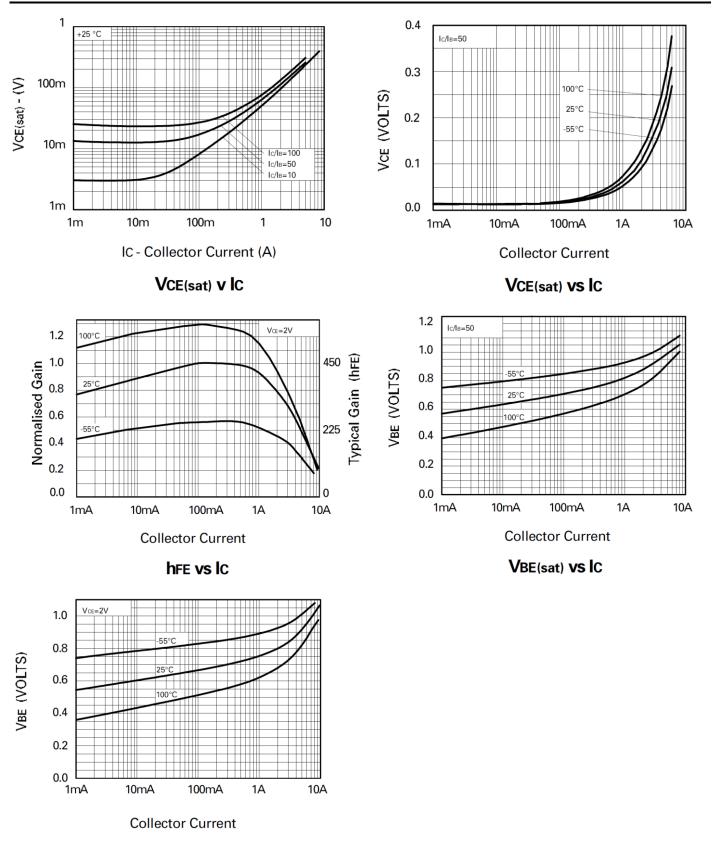
NPN - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Note: 8. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



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NPN – Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)





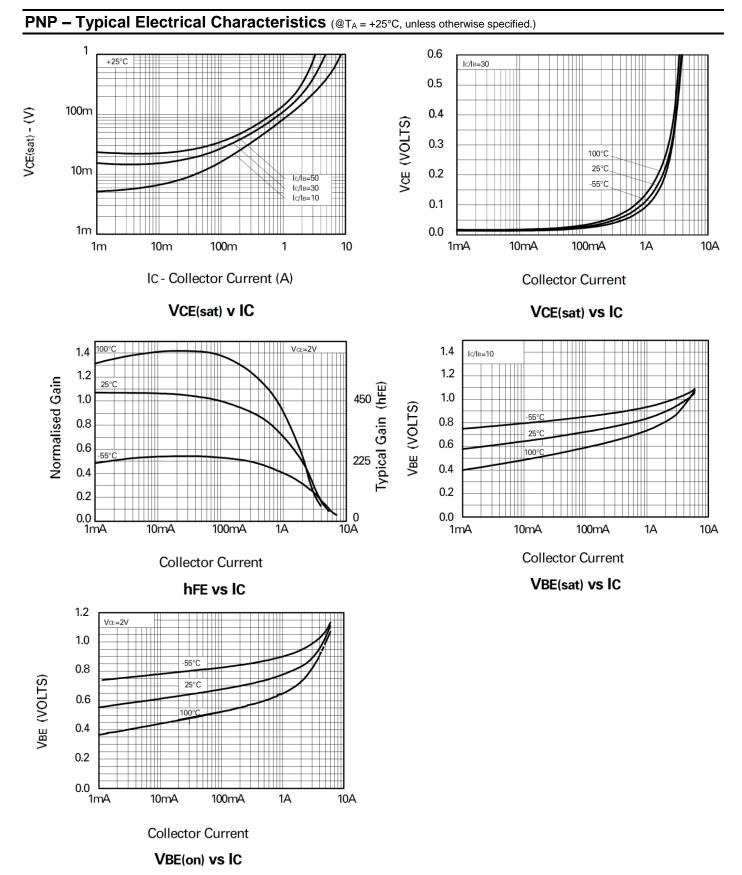
PNP - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-20	-65	_	V	I _C = -100μΑ
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	-20	-55	_	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	-8.8	—	V	I _E = -100μA
Collector Cutoff Current	I _{СВО}	—	_	-0.1	μA	V _{CB} = -15V
Emitter Cutoff Current	I _{EBO}	—	_	-0.1	μΑ	$V_{EB} = -4V$
		300	475	—	_	$I_{C} = -10 \text{mA}, V_{CE} = -2 \text{V}$
		300	450	—		$I_{C} = -100 \text{mA}, V_{CE} = -2 \text{V}$
DC Current Transfer Static Ratio (Note 9)	h _{FE}	150	230	—		$I_{C} = -2A, V_{CE} = -2V$
		35	70	—		$I_{C} = -4A, V_{CE} = -2V$
		—	30	—		$I_{C} = -6A, V_{CE} = -2V$
	V _{CE(sat)}	—	-16	-40	mV	I _C = -100mA, I _B = -10mA
Collector-Emitter Saturation Voltage (Note 9)		_	-130	-200		I _C = -1A, I _B = -20mA
		_	-190	-260		I _C = -2.5A, I _B = -200mA
Base-Emitter Saturation Voltage (Note 9)	V _{BE(sat)}	—	-0.98	-1.1	V	I _C = -2.5A, I _B = -200mA
Base-Emitter Turn-on Voltage (Note 9)	V _{BE(on)}	—	-0.85	—	V	I _C = -2.5A, V _{CE} = -2V
Transitional Frequency	f⊤	150	180	—	MHz	I _C = -50mA, V _{CE} = -10V, f = 100MHz
Output Capacitance	C _{obo}	_	21	30	pF	V _{CB} = -10V, f = 1MHz
Switching Time	t _(ON)		40		nS	V _{CC} = -10V, I _C = -1A,
	t _(OFF)] —	670	_	nS	$I_{B1} = -I_{B2} = -20mA$

Note: 9. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



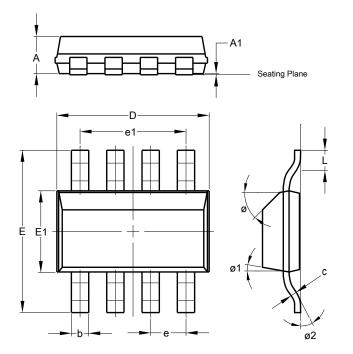
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Package Outline Dimensions

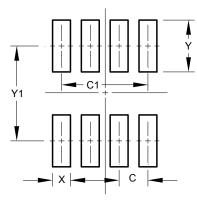
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	S	M-8		
Dim	Min	Max	Тур	
Α		1.70	1.60	
A1	0.02	0.10	0.04	
b	0.70	0.90	0.80	
С	0.24	0.32	0.28	
D	6.30	6.70	6.60	
е	1.53 REF			
e1		4.59 RE	F	
Е	6.70	7.30	7.00	
E1	3.30	3.70	3.50	
L	0.75	1.00	0.90	
Ø			45°	
Ø1		15°		
Ø2			10°	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	1.52		
C1	4.60		
Х	0.95		
Y	2.80		
Y1	6.80		

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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